What Is Claimed Is:

1. A connection structure, comprising first electrodes on a first substrate and second electrodes on a second substrate which are electrically connected with an interposed isotropic electroconductive adhesive layer, wherein said connection structure satisfies Eq. 1 below

$$0.5\times\{(A^1C^1 + A^2C^2)/(B+C)\} \leqq X \leqq 2\times\{(A^1C^1 + A^2C^2)/(B+C)\} \quad (1)$$

where A^1 is the height of each first electrode, B^1 is the electrode width thereof, C^1 is the width of the interelectrode space, A^2 is the height of each second electrode, B^2 is the electrode width thereof, C^2 is the width of the interelectrode space (provided that $B+C = B^1+C^1 = B^2+C^2$), and X is the thickness of the electroconductive adhesive layer prior to connection.

2. A connection method for electrically connecting first electrodes on a first substrate and second electrodes on a second substrate with an interposed anisotropic electroconductive adhesive layer, wherein said connection method satisfies Eq. 1 below

$$0.5\times\{(A^1C^1 + A^2C^2)/(B+C)\} \leqq X \leqq 2\times\{(A^1C^1 + A^2C^2)/(B+C)\} \quad (1)$$

where A^1 is the height of each first electrode, B^1 is the electrode width thereof, C^1 is the width of the interelectrode space, A^2 is the height of each second electrode, B^2 is the electrode width thereof, C^2 is the width of the interelectrode space (provided that $B+C = B^1+C^1 = B^2+C^2$), and X is the thickness of the electroconductive adhesive layer prior to connection.

3. A film connector in which conductor layers are formed on a flexible resin film substrate, a cover film is laid over these conductor layers such that the conductor layers are exposed at the two ends of the flexible resin film substrate, and anisotropic electroconductive adhesive layers are formed in the areas of the conductor layers not covered by the cover film, wherein said film connector has a configuration in which the thickness of the anisotropic electroconductive adhesive layers, the height of the conductor layers at the two ends of the flexible resin film substrate, the width of the conductor layers, and the width of the space between the conductor layers are selected such that the electrode height of the components to be connected by means of the film connector, the electrode width, and the width of the interelectrode space satisfy the requirements of the connection method defined in Claim 2.

4. A film connector as defined in Claim 3, wherein the anisotropic electroconductive adhesive layers at the two ends of the flexible resin film substrate have mutually different thicknesses.

5. A film connector as defined in Claim 4, wherein the thickness of one anisotropic electroconductive adhesive layer is at least 1.5 times the thickness of the other anisotropic electroconductive adhesive layer.